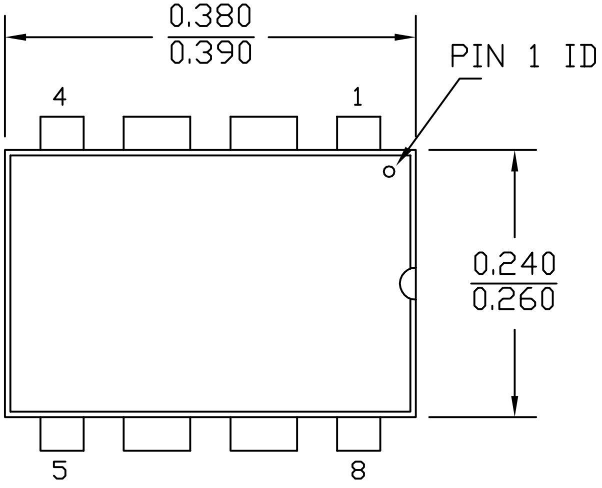
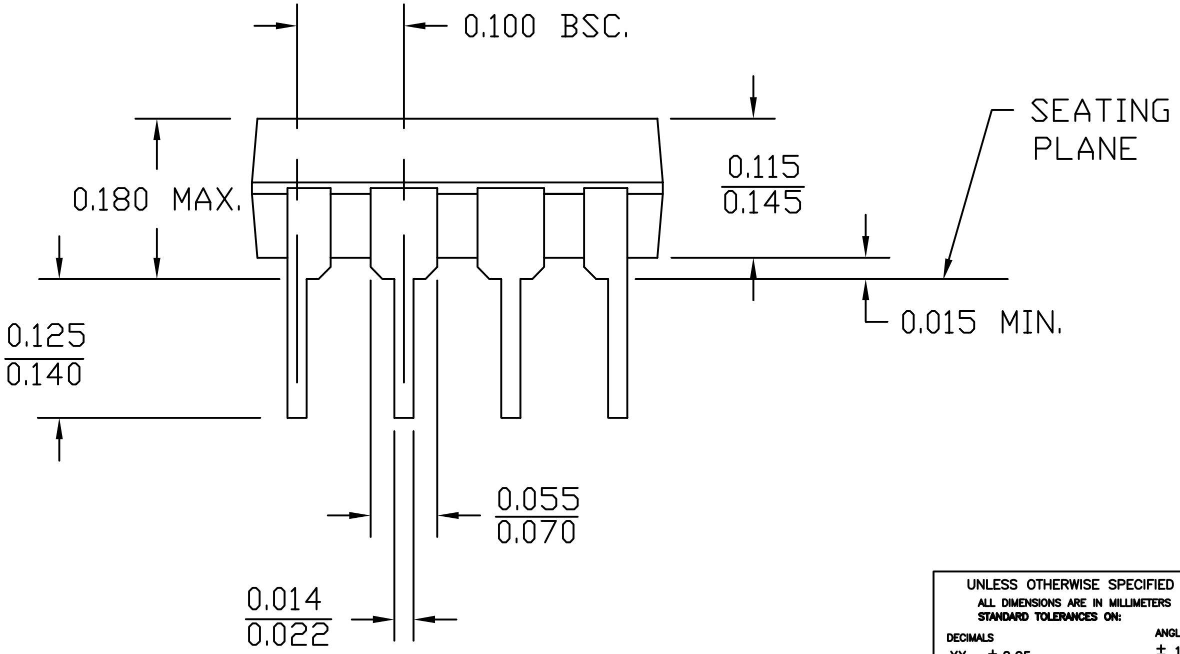
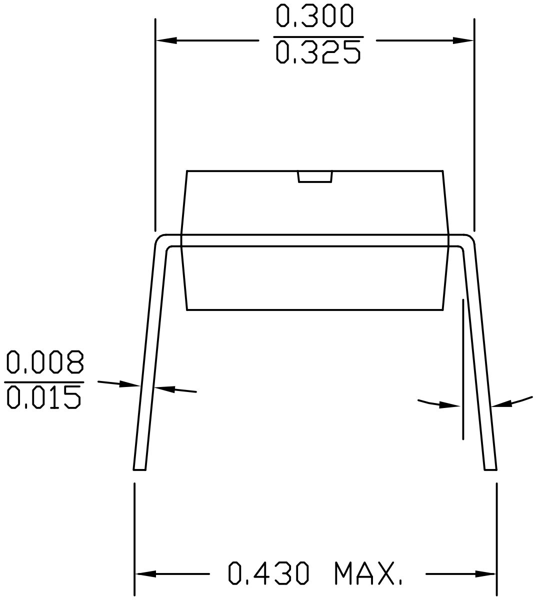
8 Lead (300 Mil) PDIP

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	–	**	1550	NEW RELEASE	04/01/96	N/A
1	–	*A	49422	CHG. TITLE	04/03/97	N/A
1	–	*B	2835564	Changed template, & title from 8LD (300 MIL) PDIP PKG OUTLINE to PACKAGE OUTLINE, 8LD PDIP 300 MILS P08.3.	12/28/09	QAD
1	–	*C	3278498	NO CHANGE. SUNSET REVIEW.	06/09/11	N/A



DIMENSIONS IN INCHES $\frac{\text{MIN.}}{\text{MAX.}}$





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UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS ARE IN MILLIMETERS
STANDARD TOLERANCES ON:
DECIMALS
.XX ± 0.05
.XXX ±
.XXXX +
ANGLES
± 1°

MATERIAL N/A
FINISH N/A

DESIGNED BY	HTN	DATE	04/03/97
DRAWN BY	HTN	DATE	04/03/97
CHECKED BY	TSV	DATE	06/09/11
APPROVED BY	QAD	DATE	06/09/11
APPROVED BY	ECVI	DATE	06/09/11
APPROVED BY	N/A	DATE	N/A

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TITLE PACKAGE OUTLINE, 8LD PDIP 300 MILS P08.3

SIZE	PART NO.	DWG NO	REV
A	P08.3	51–85075	*C

SCALED TO FIT N/A SHEET 1 OF 1